L Number	Hits	Search Text	DB	Time stamp
1	0	(((((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire)) same ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4)) same ((hot heat$4 warm$4 temperature) near4 (platform plate$2 surface base support$4))) and ((pull$4 tear$4 tension$4 separat$4 remov$4 strength detach$4 stretch$4 draw$4) near6 (measur$4 meter$4 estimat$4 detect$4 determin$4 test$4 sens$4 monitor$4 bond$4) near4 (forc$4 load$4 strain$4 stress$4))) and "180.degree. C." and ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 13:00
2	0	"180.degree. C." same ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 12:58
3	0	"180.degree. C." and ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 12:59
4	0	"180.degree. C." and ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 12:59
5	0	".degree. C." and ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 12:59
6	10018	degree?C and ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 14:48
7	74	(degree?C and ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4))) and ((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire)) same ((polymer$4 elastomer$4 plastic$4) same ((hot heat$4 warm$4 temperature) near4 (platform plate$2 surface base support$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 14:47
8	51	((degree?C and ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4))) and ((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire)) same ((polymer$4 elastomer$4 plastic$4) same ((hot heat$4 warm$4 temperature) near4 (platform plate$2 surface base support$4)))) and ((metal$4 nickel alum$4 iron silver gold copper) near4 (film layer plate sheet board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 14:55
10	8887	(degree?f or degree?C) and ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 14:49
9	35	(degree?C and ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4))) and ((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire)) same ((polymer$4 elastomer$4 plastic$4) near5 (hot heat$4 warm$4 temperature) near4 (bind$4 cur$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 14:51

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12	24	((degree?f or degree?C) and ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4))) and ((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire)) same ((polymer$4 elastomer$4 plastic$4) near5 (hot heat$4 warm$4 temperature) near4 (bind$4 cur$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 15:04
14	2576	((degree?f or degree?C) and ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4))) and ((metal$4 nickel alum$4 iron silver gold copper) near4 (film layer plate sheet board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 14:57
15	2576	((degree?f or degree?C) and ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4))) and ((metal$4 nickel alum$4 iron silver gold copper) near4 (film layer plate sheet board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 14:57
16	6	((degree?f or degree?C) and ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4))) and ((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire)) and ((polymer$4 elastomer$4 plastic$4) near5 (hot heat$4 warm$4 temperature) near4 (bind$4 cur$4) near6 ((metal$4 nickel alum$4 iron silver gold copper) near4 (film layer plate sheet board)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 15:07
17	4	((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire)) same (polymer$4 near5 (hot heat$4 warm$4 temperature) near4 (bind$4 cur$4) near6 ((metal$4 nickel alum$4 iron silver gold copper) near4 (film layer plate sheet board)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 15:07
-	213	73/827.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:16
-	123	73/834.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:16
-	47	73/835.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:16
-	2993	((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire) near4 (metal$4 plate)) same (polymer$4 plastic$4) same (hot heat$4 warm$4 temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:40
-	35	(((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire) near4 (metal$4 plate)) same (polymer$4 plastic$4) same (hot heat$4 warm$4 temperature)) and ((pull$4 tear$4 tension$4 separat$4 remov$4 stretch$4 draw$4) near6 (measur$4 meter$4 estimat$4 detect$4 determin$4 sens$4) near4 (forc$4 load$4 strain$4 stress$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:45
-	310	((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire) near4 (metal$4 plate)) same ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 deposit$4 set$4)) same (hot heat$4 warm$4 temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:46

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-		9	((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire) near4 (metal$4 near4 plate)) same ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 deposit$4 set$4)) same (hot heat$4 warm$4 temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 10:36
-		7	((((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire) near4 (metal$4 plate)) same ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 deposit$4 set$4)) same (hot heat$4 warm$4 temperature)) and ((pull$4 tear$4 tension$4 separat$4 remov$4 detach$4 stretch$4 draw$4) near6 (measur$4 meter$4 estimat$4 detect$4 determin$4 sens$4 monitor$4) near4 (forc$4 load$4 strain$4 stress$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:55
-		75	((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire) near4 (metal$4 near4 plate)) and ((((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 deposit$4 set$4)) same (hot heat$4 warm$4 temperature))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:59
-		0	((((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire) near4 (metal$4 near4 plate)) and ((((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 deposit$4 set$4)) same (hot heat$4 warm$4 temperature))) and ((pull$4 tear$4 tension$4 separat$4 remov$4 detach$4 stretch$4 draw$4) near6 (measur$4 meter$4 estimat$4 detect$4 determin$4 sens$4 monitor$4) near4 (forc$4 load$4 strain$4 stress$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:58
-		2548	73/$6.ccls. and ((pull$4 tear$4 tension$4 separat$4 remov$4 detach$4 stretch$4 draw$4) near6 (measur$4 meter$4 estimat$4 detect$4 determin$4 sens$4 monitor$4) near4 (forc$4 load$4 strain$4 stress$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:59
-		2	(73/$6.ccls. and ((pull$4 tear$4 tension$4 separat$4 remov$4 detach$4 stretch$4 draw$4) near6 (measur$4 meter$4 estimat$4 detect$4 determin$4 sens$4 monitor$4) near4 (forc$4 load$4 strain$4 stress$4))) and ((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate layer specimen cable wire) near4 ((metal$4 conductive) near4 (sheet layer board plate) near6 (hot heat$4 warm$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 17:11
-		2	(73/$6.ccls. and ((pull$4 tear$4 tension$4 separat$4 remov$4 detach$4 stretch$4 draw$4) near6 (measur$4 meter$4 estimat$4 detect$4 determin$4 sens$4 monitor$4) near4 (forc$4 load$4 strain$4 stress$4))) and ((secur$4 bind$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate layer specimen cable wire) near4 ((metal$4 conductive) near4 (sheet layer board plate) near6 (hot heat$4 warm$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 17:14
-		38	(73/$6.ccls. and ((pull$4 tear$4 tension$4 separat$4 remov$4 detach$4 stretch$4 draw$4) near6 (measur$4 meter$4 estimat$4 detect$4 determin$4 sens$4 monitor$4) near4 (forc$4 load$4 strain$4 stress$4))) and ((secur$4 bind$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate layer specimen cable wire sheet layer board plate) near6 (hot heat$4 warm$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 17:15
-		2	("5641913" | "5969262").PN.	USPAT	2003/08/08 17:16
-		137	((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire) near4 plate) same ((polymer$4 elastomer$4 glu$4 adhe$5 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4)) same ((hot heat$4 warm$4 temperature) near4 (platform plate$2 surface base support$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 11:09
-		1	(((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire) near4 plate) same ((polymer$4 elastomer$4 glu$4 adhe$5 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4)) same ((hot heat$4 warm$4 temperature) near4 (platform plate$2 surface base support$4))) and ((pull$4 tear$4 tension$4 separat$4 remov$4 detach$4 stretch$4 draw$4) near6 (measur$4 meter$4 estimat$4 detect$4 determin$4 test$4 sens$4 monitor$4) near4 (forc$4 load$4 strain$4 stress$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 12:39

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-		37	(((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire)) same ((polymer$4 elastomer$4 glu$4 adhe$5 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4)) same ((hot heat$4 warm$4 temperature) near4 (platform plate$2 surface base support$4))) and ((pull$4 tear$4 tension$4 separat$4 remov$4 detach$4 stretch$4 draw$4) near6 (measur$4 meter$4 estimat$4 detect$4 determin$4 test$4 sens$4 monitor$4) near4 (forc$4 load$4 strain$4 stress$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 13:21
-		2	6455152.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 12:46
-		65	(((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire)) same ((polymer$4 elastomer$4 glu$4 adhe$5 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4)) same ((hot heat$4 warm$4 temperature) near4 (platform plate$2 surface base support$4))) and ((pull$4 tear$4 tension$4 separat$4 remov$4 strength detach$4 stretch$4 draw$4) near6 (measur$4 meter$4 estimat$4 detect$4 determin$4 test$4 sens$4 monitor$4 bond$4) near4 (forc$4 load$4 strain$4 stress$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 16:13
-		81	(((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire)) same ((polymer$4 elastomer$4 glu$4 adhe$5 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4)) same ((hot heat$4 warm$4 temperature) near4 (platform plate$2 surface base support$4))) and ((pull$4 tear$4 tension$4 separat$4 remov$4 strength detach$4 stretch$4 draw$4) near6 (measur$4 meter$4 estimat$4 detect$4 determin$4 test$4 sens$4 monitor$4 bond$4) near4 (forc$4 load$4 strain$4 stress$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 11:08
-		11	(((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire) near4 (metal$4)) same ((polymer$4 elastomer$4 glu$4 adhe$5 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4)) same ((hot heat$4 warm$4 temperature) near4 (platform plate$2 surface base support$4))) and ((pull$4 tear$4 tension$4 separat$4 remov$4 strength detach$4 stretch$4 draw$4) near6 (measur$4 meter$4 estimat$4 detect$4 determin$4 test$4 sens$4 monitor$4 bond$4) near4 (forc$4 load$4 strain$4 stress$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 17:13
-		26	(((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire)) same ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4)) same ((hot heat$4 warm$4 temperature) near4 (platform plate$2 surface base support$4))) and ((pull$4 tear$4 tension$4 separat$4 remov$4 strength detach$4 stretch$4 draw$4) near6 (measur$4 meter$4 estimat$4 detect$4 determin$4 test$4 sens$4 monitor$4 bond$4) near4 (forc$4 load$4 strain$4 stress$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 11:47
-		0	((((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire)) same ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4)) same ((hot heat$4 warm$4 temperature) near4 (platform plate$2 surface base support$4))) and ((pull$4 tear$4 tension$4 separat$4 remov$4 strength detach$4 stretch$4 draw$4) near6 (measur$4 meter$4 estimat$4 detect$4 determin$4 test$4 sens$4 monitor$4 bond$4) near4 (forc$4 load$4 strain$4 stress$4))) and "180.degree. C."	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 11:48
-		0	((((secur$4 fix$4 adher$4 bond$4 join$4 glu$4 stick$4 attach$4) near6 (film substrate specimen cable wire)) same ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4)) same ((hot heat$4 warm$4 temperature) near4 (platform plate$2 surface base support$4))) and ((pull$4 tear$4 tension$4 separat$4 remov$4 strength detach$4 stretch$4 draw$4) near6 (measur$4 meter$4 estimat$4 detect$4 determin$4 test$4 sens$4 monitor$4 bond$4) near4 (forc$4 load$4 strain$4 stress$4))) and "177.degree. C." and ((polymer$4 elastomer$4 plastic$4) near4 (appli$5 apply$4 put$4 bind$4 deposit$4 set$4 cur$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 12:55

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